

Product/Process Change Notifications



PCN - 18 060

Amphenol Information Communication and Commercial Products Group
www.amphenol-icc.com

Release Date: September 04 2018

Product Name:	PCIE Gen5 SMT		
	PCIE Gen5 SMT		
Product Manager:	Bonnie Liu		
Subject:	Notification of Change with Immediate Effectivity		
Distribution:	Affected customers		
Type of Change:	Materials Change		
Change Description:	Existing material for PCIe Gen5 SMT housing is "PA9T". This material will change to "LCP" No change of finish good part numbers. for the product series 10144667*. Before change: Finished good part number series 10144667* material is " PA9T" After change: Finished good part number series 10144667* material is "LCP"		
Reason for Change:	Product improvement. LCP resin have better warpage control at housing level and more resistant to reflow temperature. Therefore coplanarity of solder tails are more stable during reflow process.		
Affected Parts:	See Affected Parts.xls file		
Effective Date of Change:	September 15, 2018		
Last Time Buy Date:			
Earliest Disty Return Date:			
Last Time Shipment Date			
Datasheet Attached?	NA		
Qual/Test Data Attached?	NA		
Samples Availability Date:	June	20	2018
Available Alternatives?	N/A		
Questions?	<i>Contact your local AICC Representative, or Product Manager</i>		
	<i>Bonnie Liu / Product Manager</i>		
	<i>+86 769 88669459/ Bonnie.liu@fci.com</i>		

Note:

Customers should contact Product Manager (or their local AFCI /AICC Representative) directly regarding any concern on the PCN. Lack of any such customer feedback within three weeks of PCN release date will be interpreted as non-objection .